WHAT IS CLAIMED IS:

1. A method of securing a panel with an adhesive bonding material, using hand-held operator manipulatable dispensing device to dispense adhesive bonding material via a dispensing outlet of the device, the method comprising subjecting the bonding material to a predetermined temperature regime, the predetermined temperature regime having:

(i) a period of heating the bonding material at a predetermined level prior to dispensing from the dispensing outlet of the device; and

(ii) a subsequent period of curing in-situ in contact with the glazing panel at a temperature significantly below the heating temperature level in step (i); wherein

the temperature of the adhesive bonding material dispensed via the dispensing outlet is maintained substantially uniform as adhesive is dispensed about the periphery of the panel.

2. A method according to claim 1, wherein the adhesive bonding material is a moisture cure adhesive bonding material.

3. A method according to claim 1, wherein the predetermined level to which the adhesive bonding material is heated prior to dispensing from the dispensing device is substantially at or above 50°C.

4. A method according to claim 1, wherein the predetermined level to which the adhesive bonding material is heated prior to dispensing from the dispensing device is substantially in the range 70°C ± 20°C.

5. A method according to claim 1, wherein the temperature of the adhesive bonding material as dispensed is maintained at a uniform temperature ± 5°C during dispensing about a panel or the frame to which the panel is to be bonded.

6. A method according to claim 1, wherein the uniform dispensing temperature of the adhesive bonding material dispensed from the device is 70°C ± 20°C.

7. A method according to claim 1, wherein a minor degree of curing of the adhesive bonding material occurs during the in applicator device heating stage.

8. A method according to claim 1, wherein a bulk heating technique is utilised to heat the adhesive bonding material.

9. A method according to claim 1, wherein dielectric heating is used to heat the adhesive bonding material.

10. A method according to claim 1, wherein microwave heating is used to heat the adhesive bonding material.

11. A method according to claim 1, wherein Radio Frequency heating is used to heat the adhesive bonding material.

12. A method according to claim 1, wherein ultrasonic heating is used to heat the adhesive bonding material.

13. A method according to claim 1, wherein heating by electromagnetic radiation is used to heat the adhesive bonding material.

14. A method according to claim 1, wherein following the heating stage and dispensing the adhesive bonding material applied to secure the panel is permitted to cure in situ in ambient conditions.

15. A method according to claim 1, wherein the heating stage is carried out prior to positioning the panel and adhesive bonding material for securing.

16. An applicator device for dispensing adhesive material, the applicator device being hand-held and operator manipulatable and comprising a body portion including a delivery channel for delivery of adhesive bonding material to a dispensing outlet nozzle, the body portion further including an operator actuatable

heating arrangement for heating the adhesive bonding material in the channel, internally of the device to a predetermined temperature level to produce a substantially constant outlet dispensing temperature via the nozzle.

17. An applicator device according to claim 16, including a drive arrangement to urge the adhesive material along the delivery channel toward the outlet nozzle, actuation of the drive arrangement and the heating arrangement being by means of a common operator manipulatable actuator.

18. An applicator device according to claim 16, wherein the heating arrangement is self-contained in a body portion of the applicator device positioned forwardly of the operator manipulatable actuator.

19. An applicator device according to claim 16, wherein the heating arrangement comprises a dielectric heating arrangement to heat the adhesive bonding material.

20. An applicator device according to claim 16, wherein the heating arrangement comprises a microwave heating arrangement to heat the adhesive bonding material.

21. An applicator device according to claim 16, wherein the heating arrangement comprises a Radio Frequency heating arrangement to heat the adhesive bonding material.

22. An applicator device according to claim 16, wherein the heating arrangement comprises an ultrasonic heating arrangement to heat the adhesive bonding material.

23. An applicator device according to claims 16, wherein the device is configured to accept the adhesive material in canister or package form.